



SYMBOLS	VQ/VQG44			VQ/VQG64			VQ/VQG100		
	MILLIMETERS			MILLIMETERS			MILLIMETERS		
	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.	MIN.	NDM.	MAX.
A	~	~	1.20	~	~	1.20	~	~	1.20
A ₁	0.05	~	0.15	0.05	0.10	0.15	0.05	0.10	0.15
A ₂	0.95	1.00	1.05	0.95	1.00	1.05	0.95	1.00	1.05
D/E	12.00 BSC.			12.00 BSC.			16.00 BSC.		
D ₁ /E ₁	10.00 BSC.			10.00 BSC.			14.00 BSC.		
b	0.30	0.37	0.45	0.17	0.22	0.27	0.17	0.22	0.27
c	0.09	~	0.20	0.09	~	0.20	0.09	~	0.20
e	0.80 BSC.			0.50 BSC.			0.50 BSC.		
L	0.45	0.60	0.75	0.45	0.60	0.75	0.45	0.60	0.75
ccc	~	~	0.10	~	~	0.08	~	~	0.08
ddd	~	~	0.20	~	~	0.08	~	~	0.08
N	44			64			100		
REF.	JEDEC MS-026-ACB			JEDEC MS-026-ACD			JEDEC MS-026-AED		

NOTES:

- ALL DIMENSIONS AND TOLERANCES CONFORM TO ANSI Y14.5M-1994.
 - PACKAGE BODY DIMENSIONS "D₁/E₁" DO NOT INCLUDE MOLD PROTRUSIONS. ALLOWABLE MOLD PROTRUSIONS SHALL NOT EXCEED 0.25mm PER SIDE.
 - THE TOP OF THE PACKAGE MAY BE SMALLER THAN THE BOTTOM OF THE PACKAGE BY 0.15mm.
- ⚠ MARK ORIENTATION WITH RESPECT TO PIN-1 I.D. IF 2 OR MORE CIRCLES EXIST ON TOP OF THE PACKAGE, USE THE SMALLEST CIRCLE AS PIN-1 I.D.

44, 64, and 100-PIN PLASTIC VERY THIN QFP
(VQ44/VQG44, VQ64/VQG64, and VQ100/VQG100)

Revision History

The following table shows the revision history for this document.

Date	Version	Revision
6/18/04	1.2	Xilinx Initial Release
2/26/07	1.2.1	Minor update to clarify Note #2.